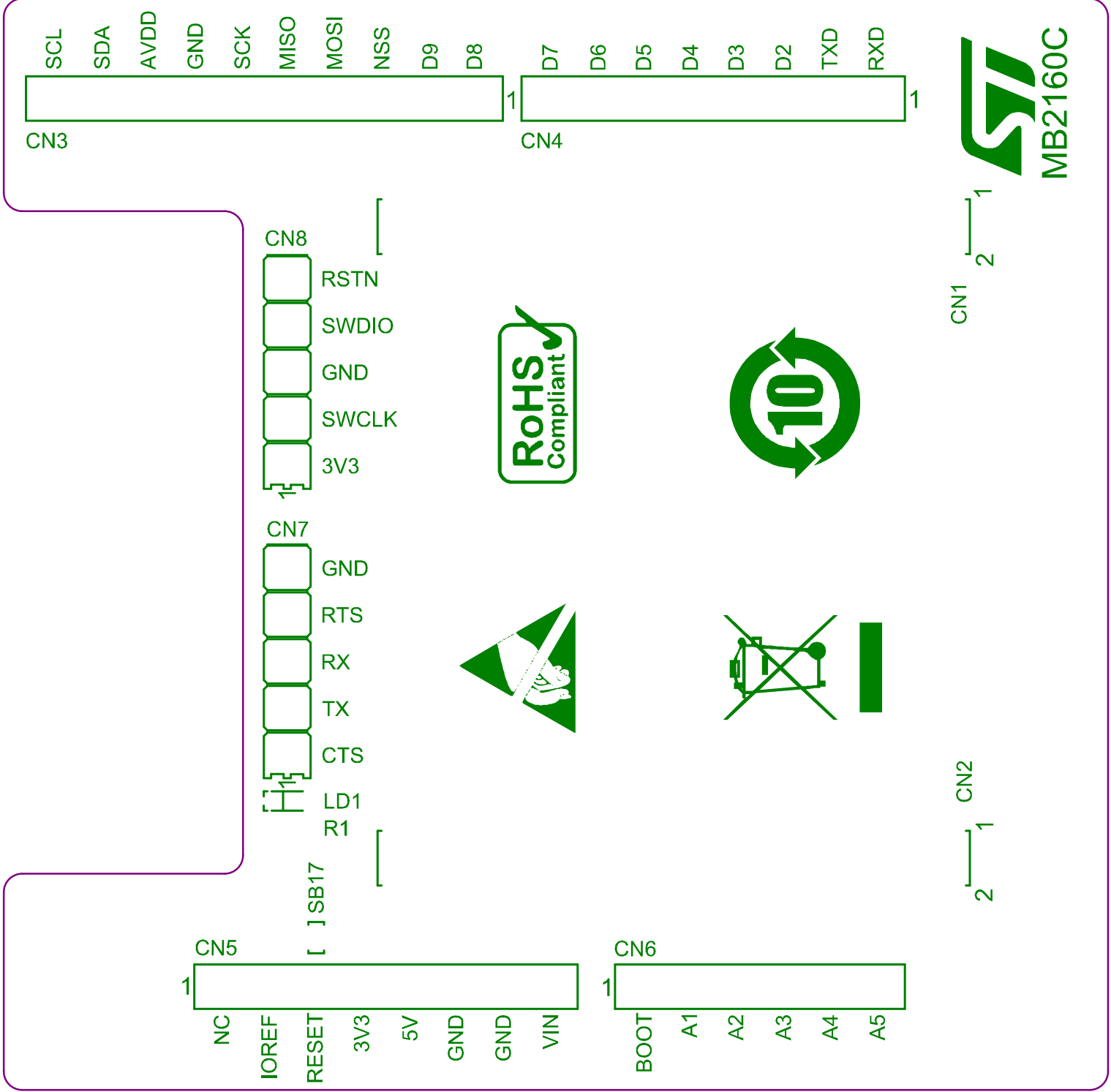
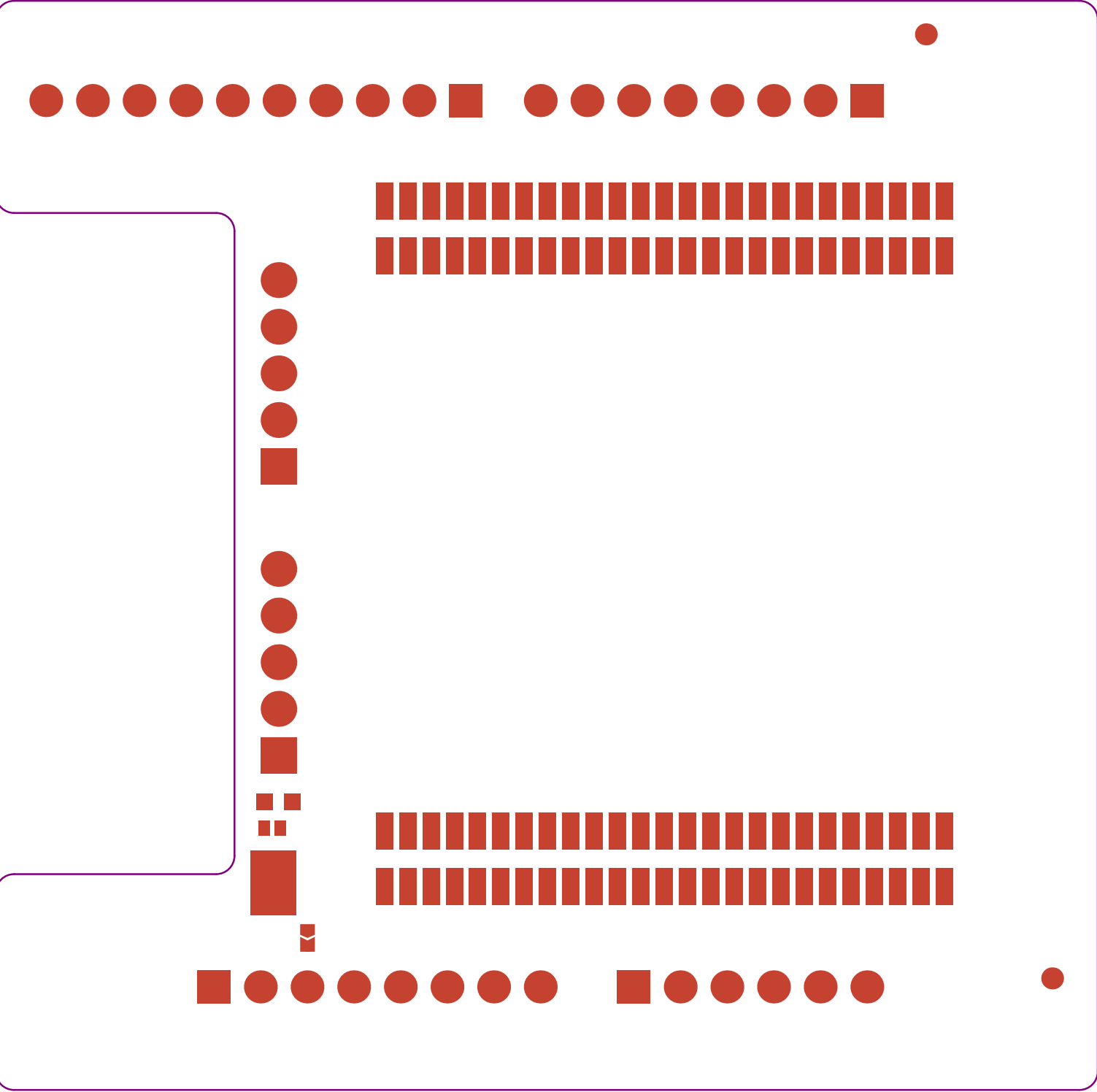




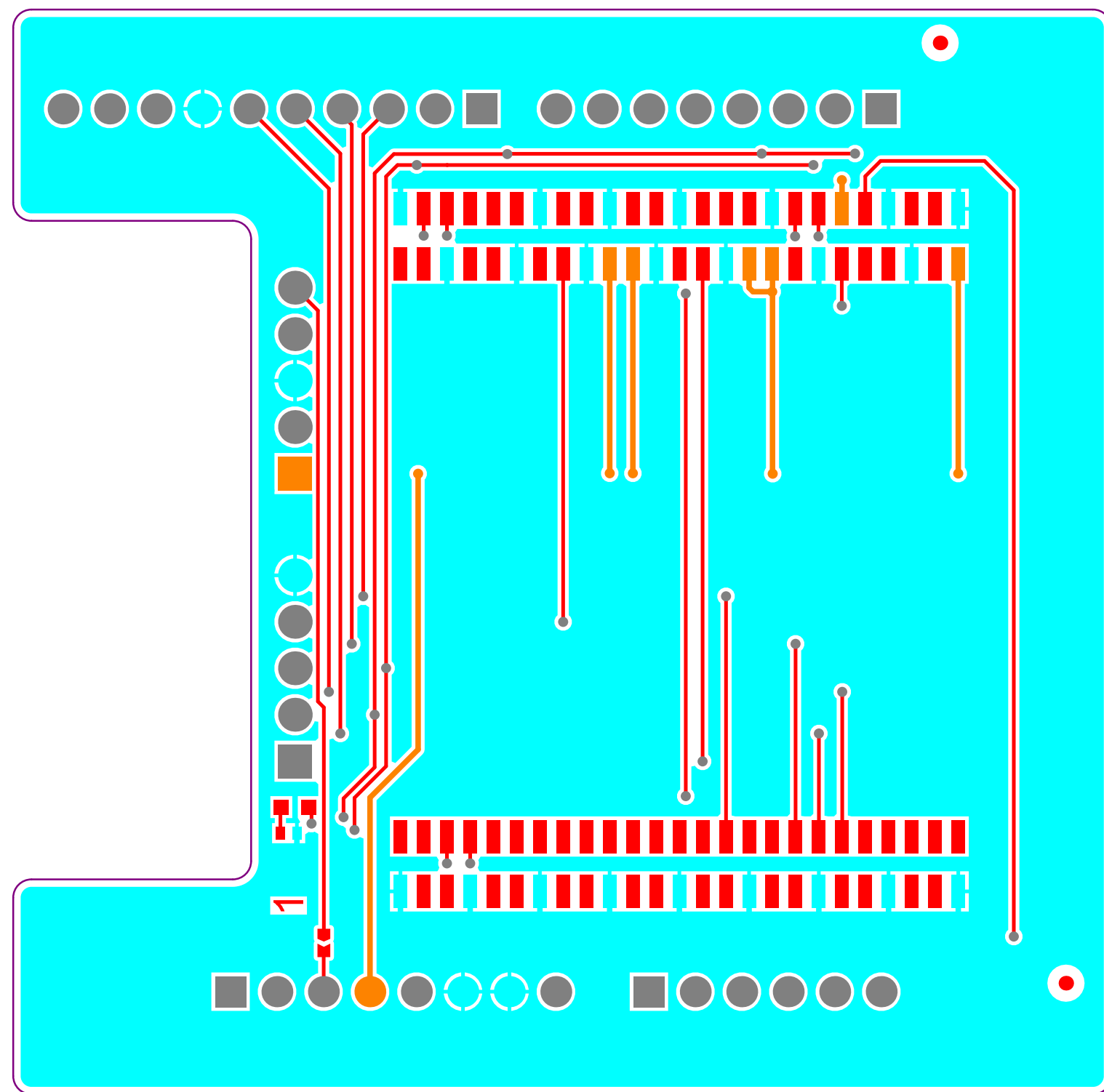
Top Overlay

.GTO



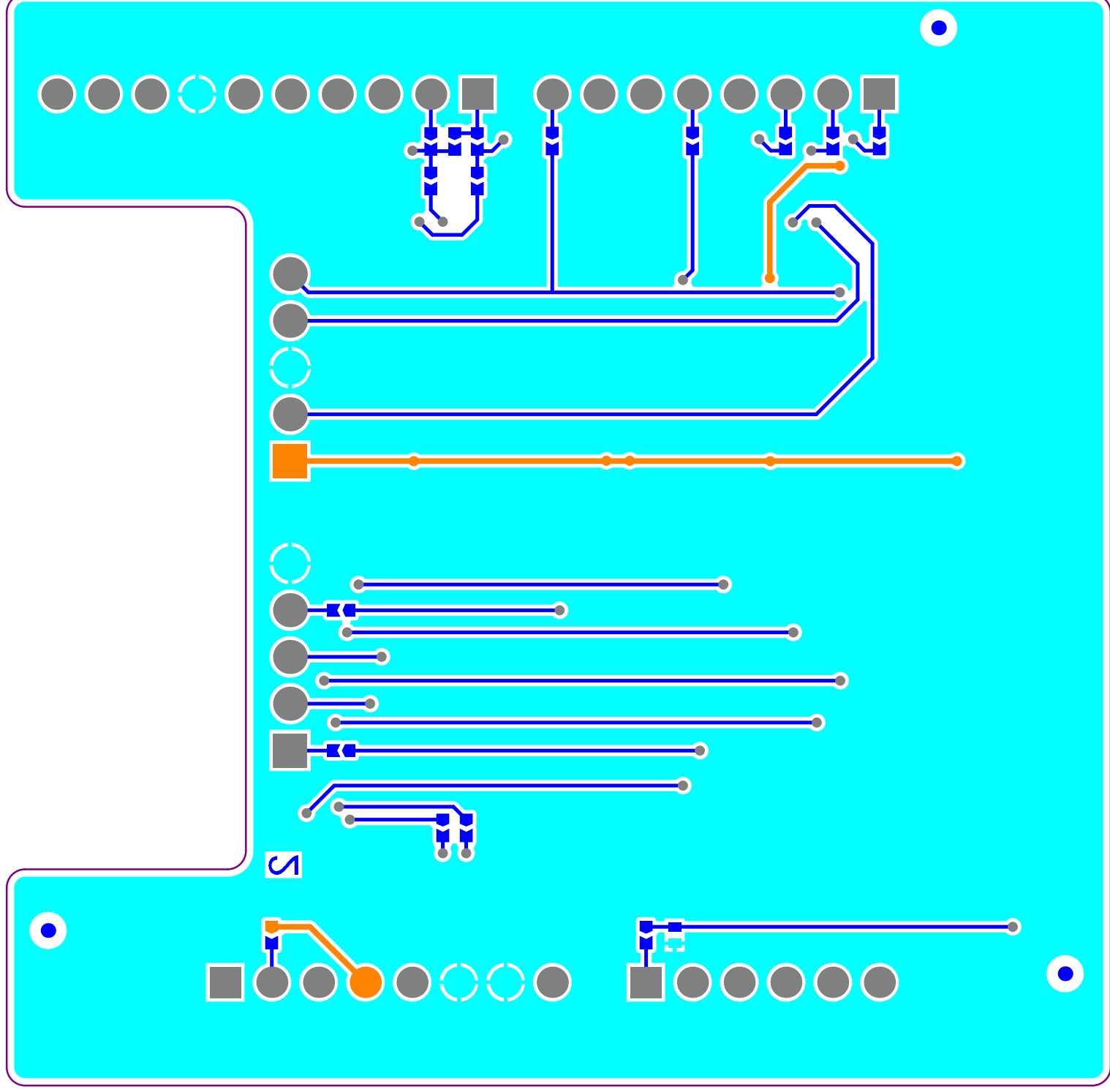
Top Solder

.GTS



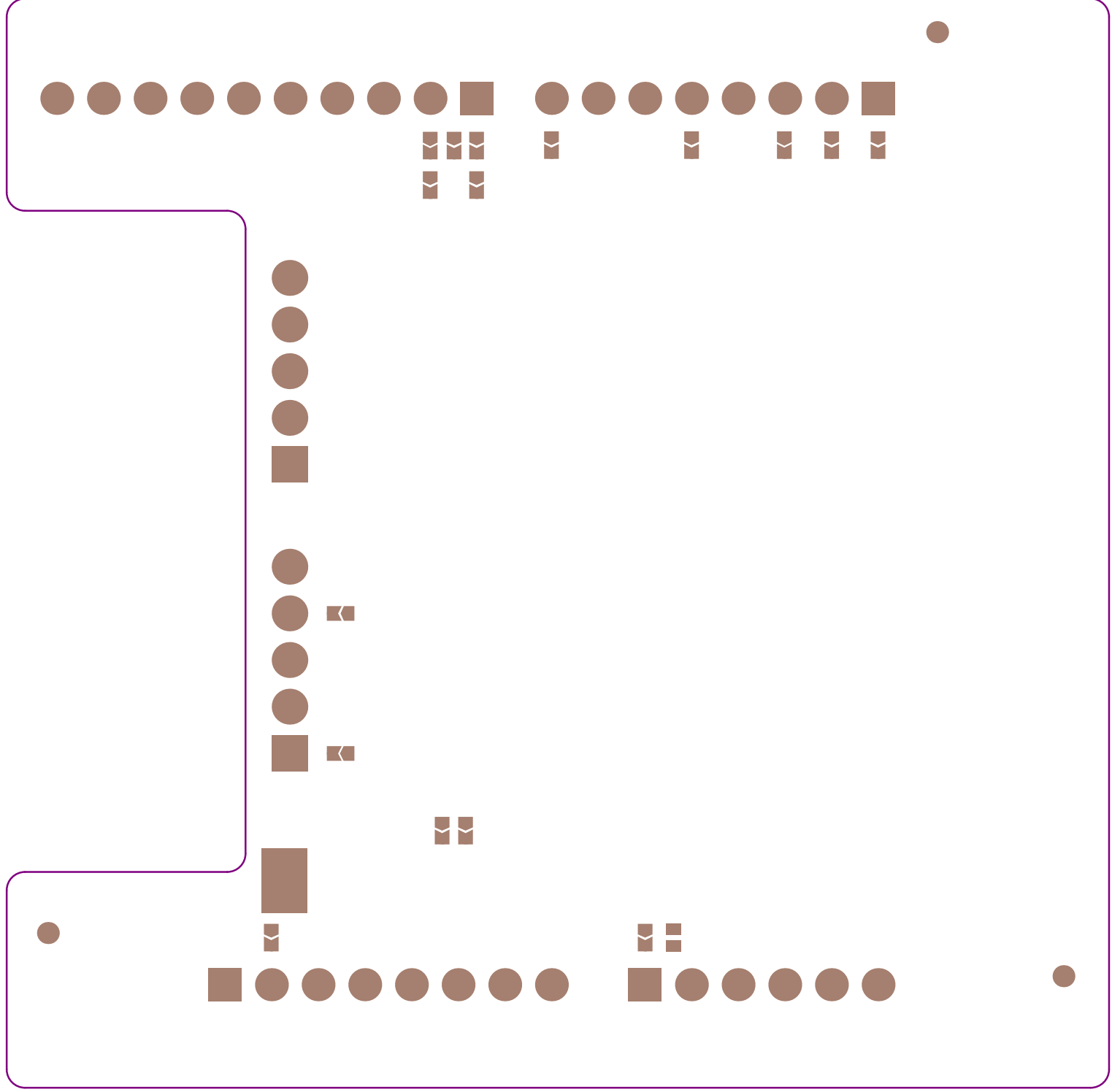
Top Layer

.GTL



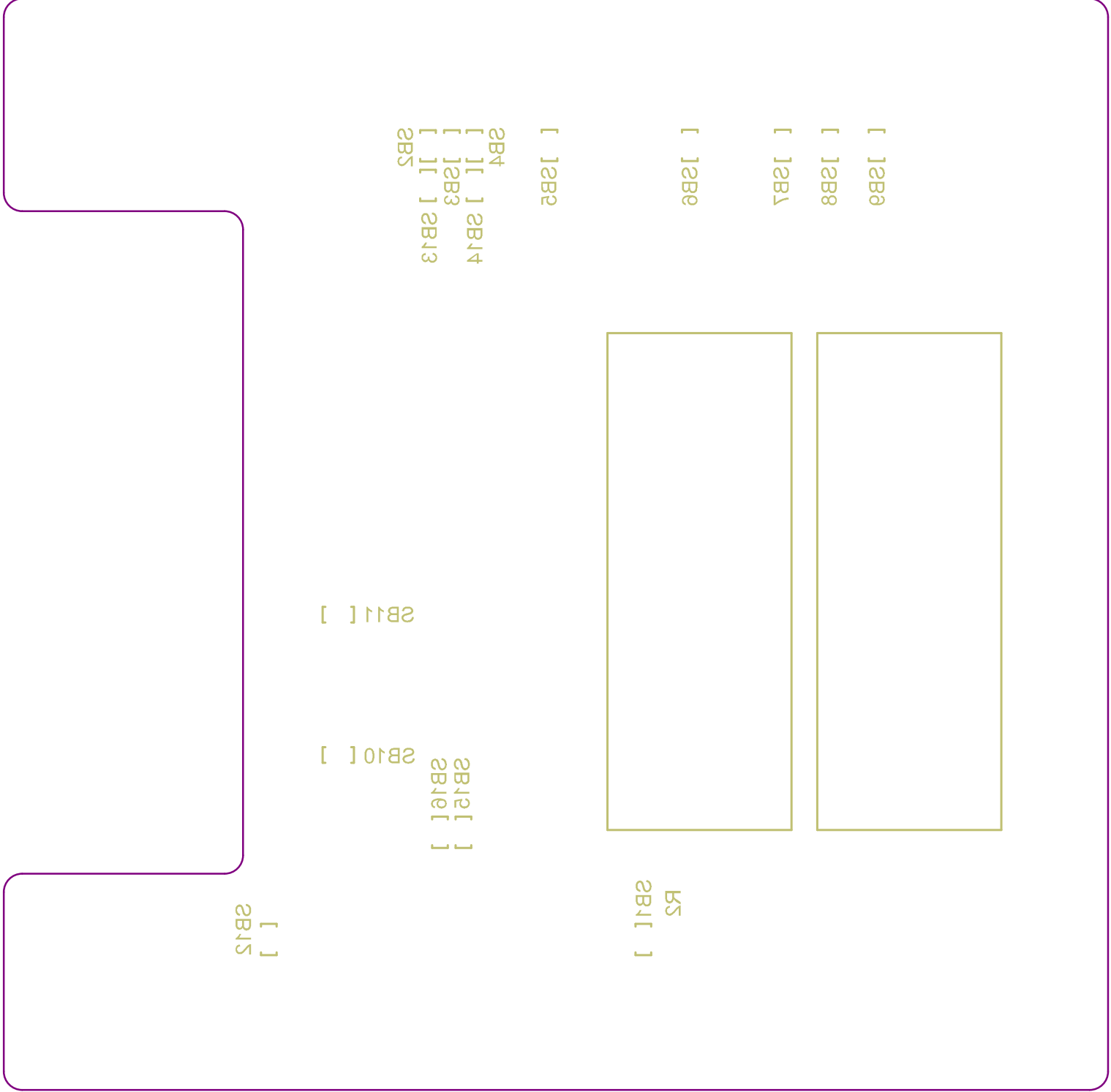
Bottom Layer

.GBL



.GB2

Bottom Solder



PCB SPECIFICATIONS :

A. MATERIAL :

FR-4

☐ TG-170

☒ TG-150

☐ TG-140

B. MATERIAL FAMILY :

N/A

C. SOLDERMASK COLOR :

☐ GREEN

☐ WHITE

☒ BLUE

☐ BLACK

D. SILKSCREEN COLOR :

☒ WHITE

☐ YELLOW

☐ BLACK

☐ Blue ink PANTONE 2955

E. SURFACE FINISH :

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

F. IMPEDANCE CONTROL :

☐ NO

☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

G. THROUGH VIA :

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.

H. STACK-UP :

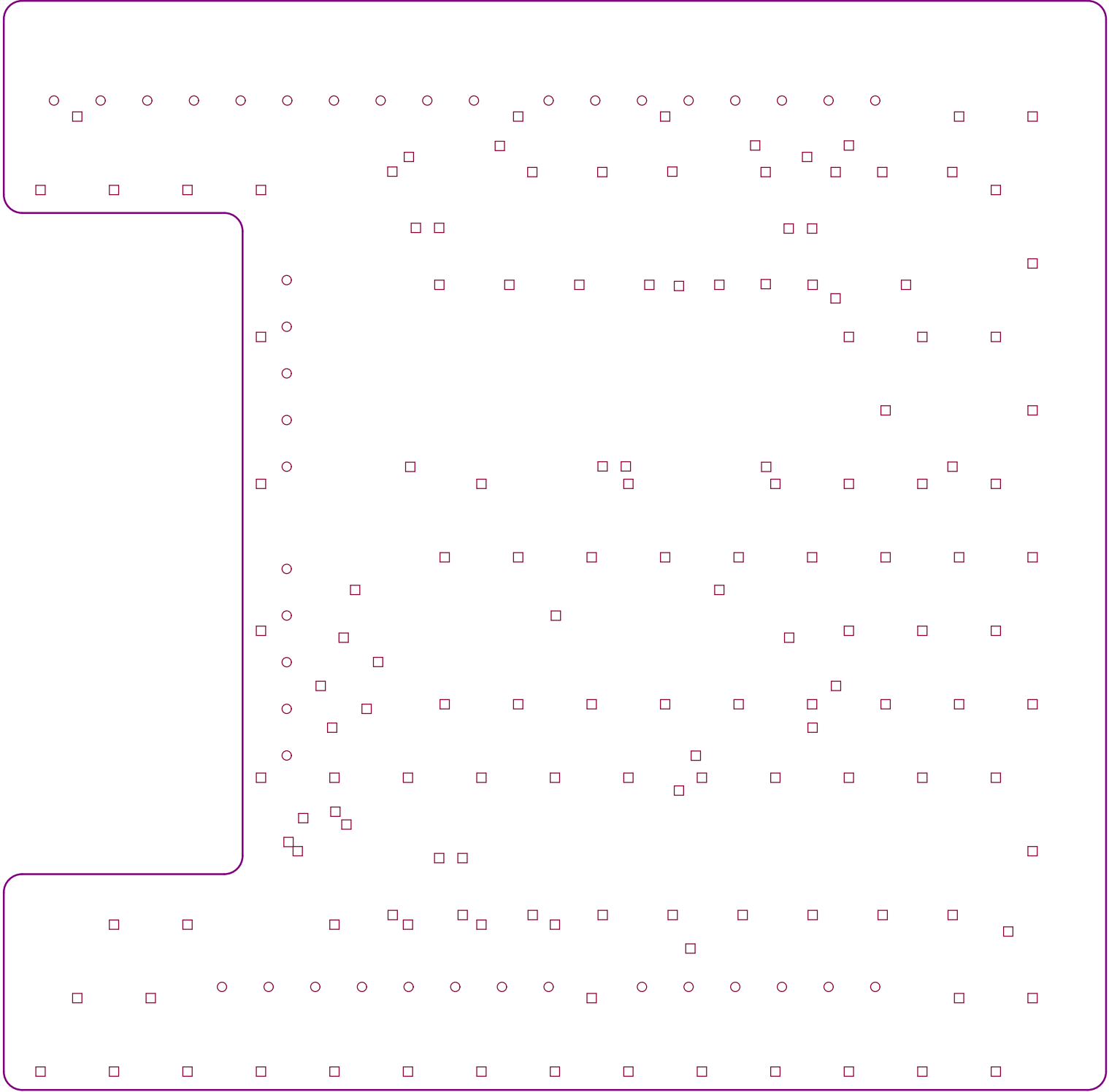
SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

PCB : TYPE 3

ASPECT-RATIO, AXE Z :

MINIMUM PARAMETERS

DEFAULT



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.59mil	3.5	
1	Top Layer		1.38mil		
	Dielectric 1	FR-4	59.06mil	4.8	
2	Bottom Layer		1.38mil		
	Bottom Solder	Solder Resist	0.59mil	3.5	
	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
	146	0.300mm (11.81mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded
	42	1.000mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)
	188 Total						